



Process Capability

Items		Parameters	Remarks
		Double Side/Multilayer	
Max Panel Size		39.37" × 23.6" (1000mm×600mm)	
Inner Layer Line Width/Space		4mil/4mil (100um/100um)	
Min Inner Layer Pad		5mil (0.13mm)	Pad Annular
Min Core Thickness		4mil (0.1mm)	
Thickness of Inner Layer Copper		0.5oz (17um)	No Cu Clad
Thickness of Outer Layer Base Copper		0.5oz (17um)	
Thickness of finished Panel		0.20 – 4.0mm	
Tolerance of Finished Panel Thickness	Thickness<1.0mm	±12%	4 – 8 layers
	1.0mm≤Thickness≤2.0mm	±8%	4 – 8 layers
		±10%	≥10 layers
	Thickness≥2.0mm	±10%	
Surface Treating Process of Inner Layer		Brown Oxide	
Number of Layers		1 – 28 layers	
Registration of Inner Layer to of Inner Layer		±3mil (±76um)	
Min Drilling Diameter		0.15mm	
Min Diameter of Finished Hole		0.10mm	
Accuracy of hole position		±2mil (±50um)	
Tolerance of Drilled Slot		±3mil (±75um)	
Tolerance of PTH Diameter		±2mil (±50um)	
Tolerance of NPTH Diameter		±1mil (±25um)	
Max A.R. of PTH		10:1	
PTH Hole Copper Thickness		0.4 – 2mil (10 – 50um)	
Image to Image Tolerance		±3mil (0.075mm)	
Min Outer Layer Line Width/Space		3mil/3mil (75um/75um)	
Tolerance of Etching		±1mil (±25um)	
Thickness of Solder Mask	Line End	0.4 – 1.2mil (10-30um)	
	Line Comer	≥0.2mil (5um)	
	On Substrate	≤finished Cu thickness+30um	
Hardness of Solder Mask		6H	
Solder Mask Registration Tolerance		±2mil (±50um)	
Min Solder Mask Dam		3mil (75um)	
Max Solder Mask Plug Hole Diameter		0.8mm	
Surface Finishing		HASL, Gold Finger, Au Panel, OSP, ENIG	
Max Nickel Thickness of Gold Finger		280u" (7um)	
Max Gold Thickness of gold Finger		60u" (1.5um)	
Range of Nickel Thickness for electroless Nickel and immersion Gold		120u"/240u" (3um/6um)	
Range of Gold Thickness for electroless Nickel and immersion Gold		2u"/6u" (0.05um/0.15um)	
Impedance Control and Tolerance		50 Ω ± 10%	
Peel Strength of Line		≥61B/in (≥107g/mm)	
Warp and Twist		≤0.5%	